2026

The 2nd Taipei-Sydney Semiconductor BootCamp

Dual-Stream Training

Advanced Packaging Lab

Global Industry Experts

Registration Period

From now until May 20, 2026
Payment Deadline: May 26, 2026

WEBSITE

semibootcamp.org

REGISTRATION

tssb2026.easyevents.org

Course Dates

Group A: June 22, 2026 to June 26, 2026
Group B: June 29, 2026 to July 3, 2026

Upon completion of the course, participants will be issued a certificate of attendance

Dr. Nadia Court	S3B Director
Dr. Chien-Yung, Ma	Chairman of Openness Specialty Materials Corp. Ltd
Dr. Yang	Former TSMC R&D Director
Prof. JY Jeng	NTUST, Global Expert in 3D Printing & Semiconductors
Prof. SH Hsu	Silicon Photonics Specialist for Advanced Packaging

Highlights of Bootcamp

Dual-Stream Tracks: Tailored for all backgrounds.

Core Focus: IC Design & Advanced Packaging.

Expert Insights: Lectures from industry leaders.

Hands-on Labs: Technical packaging demonstrations.

University Tours: Visit NYCU & NTHU research labs.

Industry Visits: TSMC, Forcera, and Actron tours.

Specialized Centers: Silicon Photonics integration labs.

Cultural Networking: Farewell dinner at Din Tai Fung.

Fee

Total tuition fee for this bootcamp:
NT 40,000/ USD 1,300 per participant

The fee covers tuition, course materials, travel insurance, a selection of meals and certificate

(Does not include accommodation and other personal expenses)

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